Solder wire STU-NP303

Product description

GENMA solder wire – our STU-NP303 solder wire convinces with its extremely quick wetting properties in laser soldering. Its quick and excellent wetting properties allow a rapid soldering process. The fast wetting speed is reducing the process time and increasing the throughput. No contamination by flux or tin spatter on the board. The flux residues are clear. Cleaning after soldering is not necessary.

Technical properties

	Specific value				Testing method
Diameter (mm)	0,15	0,3	0,5 / 0,6	0,8 / 1,0 / 1,2 / 1,6	
Weight spindle (g)	50	250	500	1000	
Flux type	ROL1, no clean				IPC J-STD-004B
Flux content (wt%)	3,18 ± 0,3				IPC-TM-650 2.3.34.1
Halide content (wt%)	<0,5				IPC-TM-650 2.3.35
Insulation resistance (Ω)	> 1 x 10^{12} (40°C 90% rel. humidity)				IPC-TM-650 2.6.3.3
Insulation resistance (Ω)	> 1 x 10^{9} (85°C 85% rel. humidity)				IPC-TM-650 2.6.3.3
Migration	non				IPC-TM-650 2.6.14
Recommended solder tip temperature (°C)	380 - 410°C				
Recommended storage (°C)	0 - 40				

Alloys

Name	Alloy	Melting temperature range	Advantages
NP303	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	217 - 221	Standard alloy, excellent wetting

Compliance

Dated 13.11.2025

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU.

Contains no substances (SVHC-list) more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006.

Contains no substances as defined by the Toxic Substance Control Act (TSCA) of the United States Environmental Protection Agency.

Contains no substances according to POP Regulation EU 2019/1021.

Contains no Per- and PolyFuluoroAlkyl Substances (PFAS).

Contains no phthalates or latex.

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Contains no substances according to California Proposition 65.